IPC  ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both This docum level parts,	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfc Information			
upplier Infor	mation								· · ·					
Company name*			Company unique ID			Unique ID Authority				Response Date*				
nsemi						I				2023-06-08				
Contact Name			Title - Contact			Phone - Contact*				Email - Contact*				
Product-Env-Stev	vards		Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized Repres	sentative*		Title - Representative			Phone - Representative*			Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Reques	Requester Item Number		Mfr Item Number Mfr Item Name			Effective Da	te Versio	on :	Manufacturing Site	W	eight*	UOM	Unit Type	
		TCP-5047UB-DT WLG		WLCSP6 4.7pf high Q PTIC in tape and reel		2023-06-08 PHM		PHM	0.	897	mg	Each		
	g Proccess Informatio									·				
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-S	STD-020 MSL Rating										
NE		$\mathbf{C}$	U Alloy	1		260		C	30	second	s <b>3</b>			
omments														
vel 1 - maximum	time at peak temperature	during solo	dering is 10-3	30 seconds										
or more informat	tion regarding material co	mposition p	olease refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaalian agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Condition										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Backside Protection Film	0.036	mg		Epoxy resin	proprietary data		0.0108	mg
			Supplier	Poly(Ethylene Terephthalate) (C10H8O4)	25038-59-9		0.0216	mg
			Supplier	Silicone polymer	Proprietary Data		0.0014	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0007	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.0011	mg
			Supplier	Acrylic resins	Proprietary Data		0.0004	mg
Plating	0.0033	mg	Supplier	Silver (Ag)	7440-22-4		0.0004	mg
			В	Nickel (Ni)	7440-02-0		0.0019	mg
			Supplier	Gold (Au)	7440-57-5		0.001	mg
Solder Ball	0.0398	mg	Supplier	Silver (Ag)	7440-22-4		0.0012	mg
			Supplier	Tin (Sn)	7440-31-5		0.0384	mg
			Supplier	Copper (Cu)	7440-50-8		0.0002	mg
Substrate	0.8179	mg	Supplier	BST (BaSrTiO3)	12430-73-8		0.001	mg
			Supplier	Silicon Nitride Si3N4	12033-89-5		0.0334	mg
			Supplier	Titanium (Ti)	7440-32-6		0.0001	mg
			Supplier	Platinum (Pt)	7440-06-4		0.0025	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0057	mg
			Supplier	Chromium (Cr)	7440-47-3		0	mg
			Supplier	Silicon (Si)	7440-21-3		0	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.772	mg
			Supplier	Copper (Cu)	7440-50-8		0	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0032	mg